Product / Package Information

Package	LFCSP - Punched, Stacked Die
Body Size (mm)	6 X 6 X 0.85 (4.5 EP)
Lead Count	40
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.76E-02	86.91	869100	31.11	311094
Thermosets	Epoxy & Phenol Resin	Proprietary	5.53E-03	12.78	127800	4.57	45746
Other inorganic materials	Carbon black	1333-86-4	1.34E-04	0.31	3100	0.11	1110
Subtotal			4.32E-02	100.00	1000000	35.79	357949

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	6.34 E-02	97.50	975000	52.50	524985
Copper & its alloys	Iron	7439-89-6	1.53 E-03	2.35	23500	1.27	12653
Copper & its alloys	Zinc	7440-66-6	7.80 E-05	0.12	1200	0.06	646
Copper & its alloys	Phosphorus	7723-14-0	1.95 E-05	0.03	300	0.02	162
Subtotal			6.50 E-02	100.00	1000000	53.84	538447

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.50 E-04	100.0	1000000	0.54	5384

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.21 E-03	100.0	1000000	1.83	18306

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	9.46 E-04	100.0	1000000	0.78	7830

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	7.61 E-03	100.0	1000000	6.30	63030

Die Attach 1

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.79 E-04	73.54	735400	0.64	6446
Other organic materials	Epoxy resin A	TS ref# 10013	7.78 E-05	7.35	73500	0.064	644
Others	Anhydride	TS ref# 10181	7.78 E-05	7.35	73500	0.064	644
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	3.11 E-05	2.94	29400	0.026	258
Other organic materials	Epoxy resin B	TS ref# 10237	3.11 E-05	2.94	29400	0.026	258
Others	Epoxy resin modifier	TS ref# 10038	3.11 E-05	2.94	29400	0.026	258
Others	Anhydride	TS ref# 10180	3.11 E-05	2.94	29400	0.026	258
Subtotal			1.06 E-03	100.0	1000000	0.88	8766

Die Attach 2

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Resin	Proprietary	1.73 E-05	50.0	500000	0.01	143
Other organic materials	Ethene, tetrafluoro-,homopolymer	9002-84-0	1.56 E-05	45.0	450000	0.01	129
Other organic materials	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8	1.73 E-06	5.0	50000	0.001	14
Subtotal			3.47 E-05	100.0	1000000	0.03	287

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.21 E-01**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary